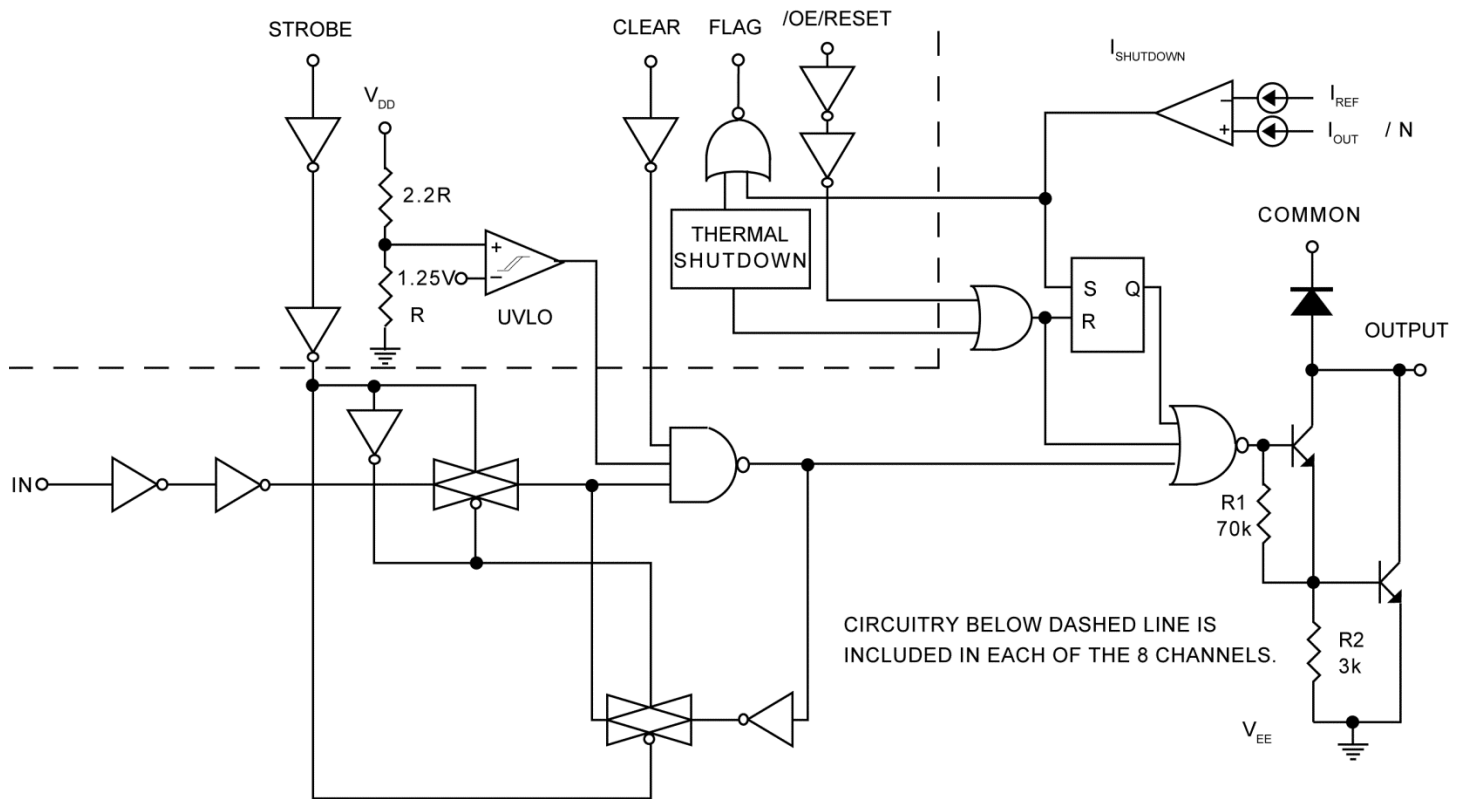


Functional Diagram



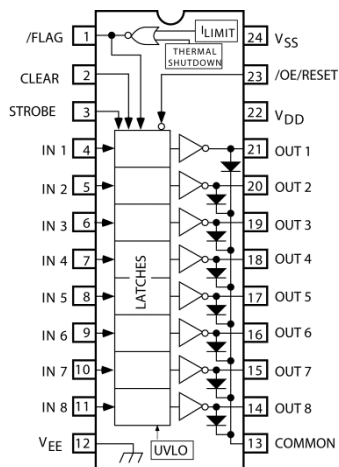
Ordering Information

Part Number	Temperature Range	Package	Pb-Free
MIC59P50YN	-40°C to +85°C	24-Pin Plastic DIP ⁽¹⁾	✓
MIC59P50YV	-40°C to +85°C	28-Pin PLCC	✓
MIC59P50YWM	-40°C to +85°C	24-Pin Wide SOIC	✓

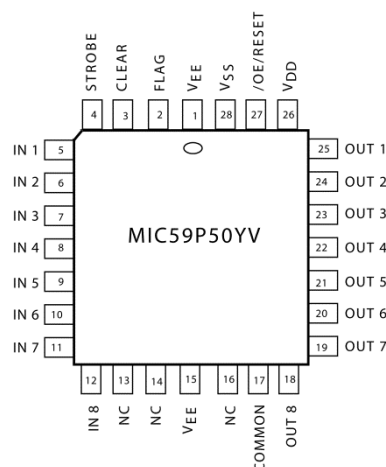
Note:

1. 300mm "Skinny DIP"

Pin Configuration



**24-Pin PDIP (N)
24-Pin Wide SOIC (WM)
(Top View)**



**28-Pin PLCC (V)
(Top View)**

Pin Description

Pin Number PDIP & SOIC	Pin Number PLCC	Pin Name	Pin Name
1	2	/FLAG	Error flag. Open-collector output is low upon overcurrent fault or overtemperature fault. /OE/RESET must be pulled high to reset the flag and fault condition.
2	3	CLEAR	Sets all latches to OFF (open).
3	4	STROBE	Input strobe pin. Loads output latches when high.
4-11	5-12	IN _n	Parallel inputs, 1 through 8.
12	15	VEE	Output ground (substrate). Most negative voltage in the system connects here.
13	17	COMMON	Transient suppression diodes cathode common pin.
14-21	18-25	OUT _n	Parallel outputs, 8 through 1.
22	26	VDD	Logic positive supply voltage.
23	27	/OE/RESET	Output enable reset. When low, outputs are active. When high, outputs are inactive and the flag and outputs are reset from a fault condition. An undervoltage condition emulates a high /OE input.
24	28	VSS	Logic reference (ground) pin.

Absolute Maximum Ratings⁽²⁾

Input Voltage (V_{CE})	+80V
Supply Voltage	
(V_{DD})	15V
($V_{DD} - V_{EE}$)	25V
Continuous Collector Current (I_C)	500mA
Protected Current ⁽⁴⁾	1.5A
Lead Temperature (soldering, 10s)	260°C
Storage Temperature (T_s)	-65°C to +150°C
ESD Rating ⁽⁵⁾	ESD Sensitive

Operating Ratings⁽³⁾

Input Voltage (V_{IN})	-0.3V to $V_{DD}+0.3V$
Operating Temperature (T_A)	-40°C to +85°C
Junction Temperature (T_J)	+150°C
Power Dissipation (P_D)	
Plastic DIP (N)	2.4W
Derate above $T_A = +25^\circ\text{C}$	24mW/°C
PLCC (V)	1.6W
Derate above $T_A = +25^\circ\text{C}$	16mW/°C
Wide SOIC (WM)	1.4W
Derate above $T_A = +25^\circ\text{C}$	14mW/°C

Electrical Characteristics⁽⁶⁾

$V_{DD} = 5V$; $T_A = 25^\circ\text{C}$, unless noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
I _{CEX}	Output Leakage Current	V _{CE} = 80V, T _A = +25°C			50	μA
		V _{CE} = 80V, T _A = +70°C			100	μA
V _{CE(SAT)}	Collector-Emitter	I _C = 100mA		0.9	1.1	V
	Saturation Voltage	I _C = 200mA		1.1	1.3	V
		I _C = 350mA		1.3	1.6	V
V _{IN(0)}	Input Voltage				1.0	V
V _{IN(1)}		V _{DD} = 12V	10.5			V
		V _{DD} = 10V	8.5			V
		V _{DD} = 5V, Note 7	3.5			V
R _{IN}	Input Resistance	V _{DD} = 12V	50	200		kΩ
		V _{DD} = 10V	50	300		kΩ
		V _{DD} = 5V	50	600		kΩ
I _{OL}	/Flag Output Current	V _{OL} = 0.4V		15		mA
I _{OH}	/Flag Output Leakage	V _{OH} = 12V		50		nA

Notes:

- Exceeding the absolute maximum ratings may damage the device.
- The device is not guaranteed to function outside its operating ratings.
- Each channel VEE connection must be designed to minimize inductance and resistance.
- Devices are ESD sensitive. Handling precautions are recommended. Human body model, 1.5k Ω in series with 100pF.
- Specification for packaged product only.
- Operation of these devices with standard TTL or DTL may require the use of appropriate pull-up resistors to ensure a minimum logic "1".

Electrical Characteristics⁽⁶⁾ (Continued)

$V_{DD} = 5V$; $T_A = 25^\circ C$, unless noted.

Symbol	Parameter	Condition	Min.	Typ.	Max.	Units
$I_{DD(ON)1}$	Supply Current One Output Active	$V_{DD} = 12V$, outputs open		3.3	4.5	mA
		$V_{DD} = 10V$, outputs open		3.1	4.5	mA
		$V_{DD} = 5V$, outputs open		2.4	3.6	mA
$I_{DD(ON) All}$	Supply Current All Outputs Active	$V_{DD} = 12V$, outputs open		6.4	10.0	mA
		$V_{DD} = 10V$, outputs open		6.0	9.0	mA
		$V_{DD} = 5V$, outputs open		4.7	7.5	mA
$I_{DD(OFF)}$	Supply Current OFF	$V_{DD} = 12V$, outputs open, inputs = 0V		3.0	4.5	mA
		$V_{DD} = 5V$, outputs open, inputs = 0V		2.2	3.6	mA
I_R	Clamp Diode Leakage Current	$V_R = 80V$, $T_A = +25^\circ C$			50	μA
		$V_R = 80V$, $T_A = +70^\circ C$			100	μA
I_{LIM}	Overcurrent Threshold	Each output		500		mA
V_{SU}	Start-up Voltage	Note 8	3.5	4.0	4.5	V
$V_{DD MIN}$	Minimum Operating V_{DD}		3.0	3.5	4.0	V
V_F	Clamp Diode Forward Voltage	$I_F = 350mA$		1.7	2.0	V
	Thermal Shutdown			165		$^\circ C$
	Thermal Shutdown Hysteresis			10		

Notes:

8. Undervoltage lockout is guaranteed to release device at no more than 4.5V and disable the device at no less than 3.0V input logic voltage.

Truth Table

IN_n	Strobe	Clear	Output Enable	OUT_n	
				t-1	t
0	1	0	0	X	OFF
1	1	0	0	X	ON
X	X	1	X	X	OFF
X	X	X	1	X	OFF
X	0	0	0	ON	ON
X	0	0	0	OFF	OFF

Note:

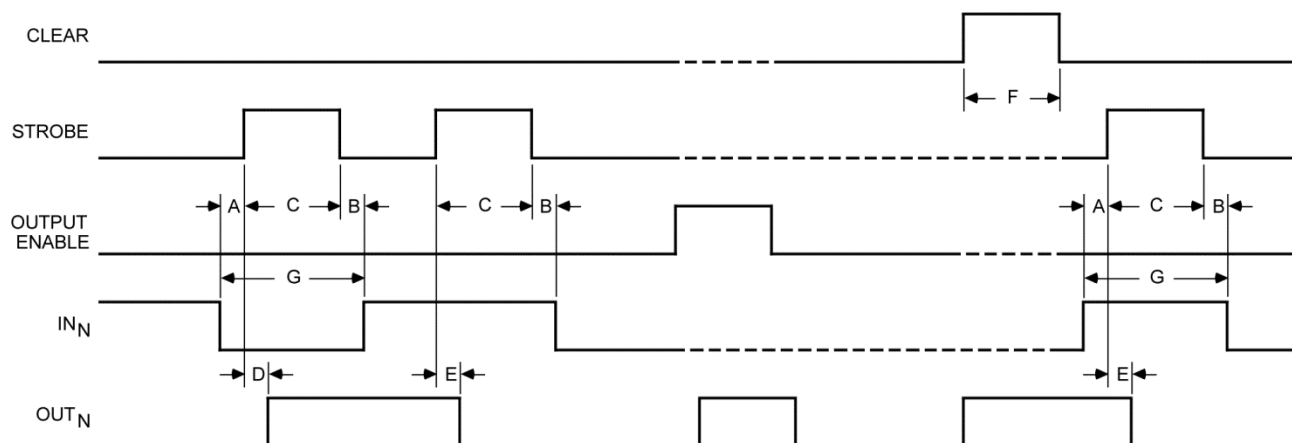
X = Irrelevant

t-1 = Previous output state

t = Present output state

Information present at an input is transferred to its latch when the STROBE is high. A high CLEAR input will set all latches to the output OFF condition regardless of the data or STROBE input levels. A high OUTPUT ENABLE will set all outputs to the OFF condition, regardless of any other input conditions. When the OUTPUT ENABLE is low, the outputs depend on the state of their respective latches. If current shutdown is activated, the OUTPUT ENABLE must be pulsed high to restore operation and reset the FLAG. Overtemperature faults are not latched and require no reset pulse.

Timing Diagram

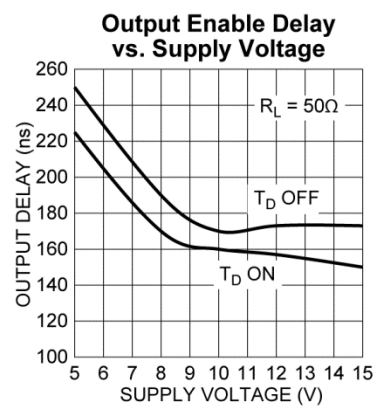
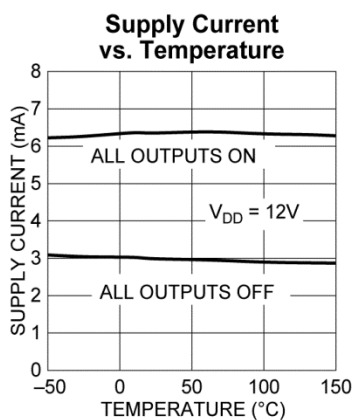
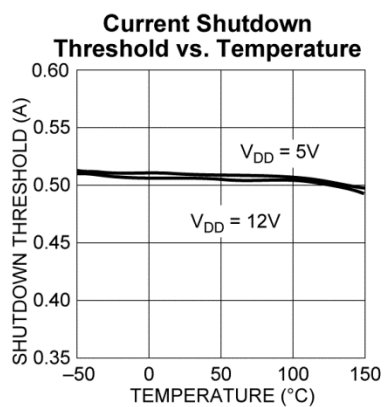
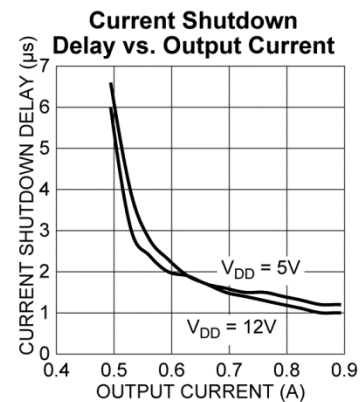
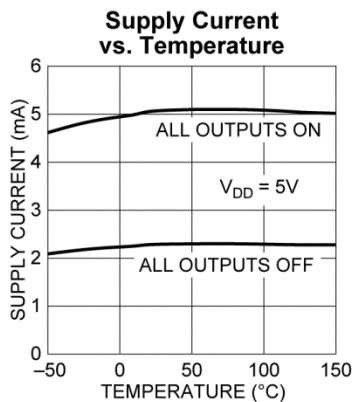
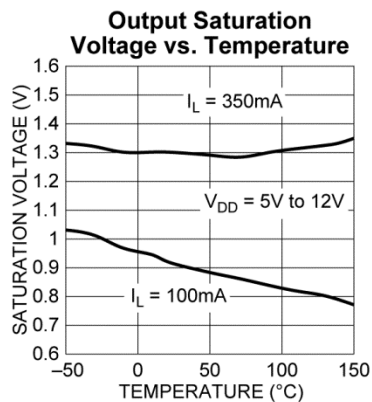


Timing Conditions

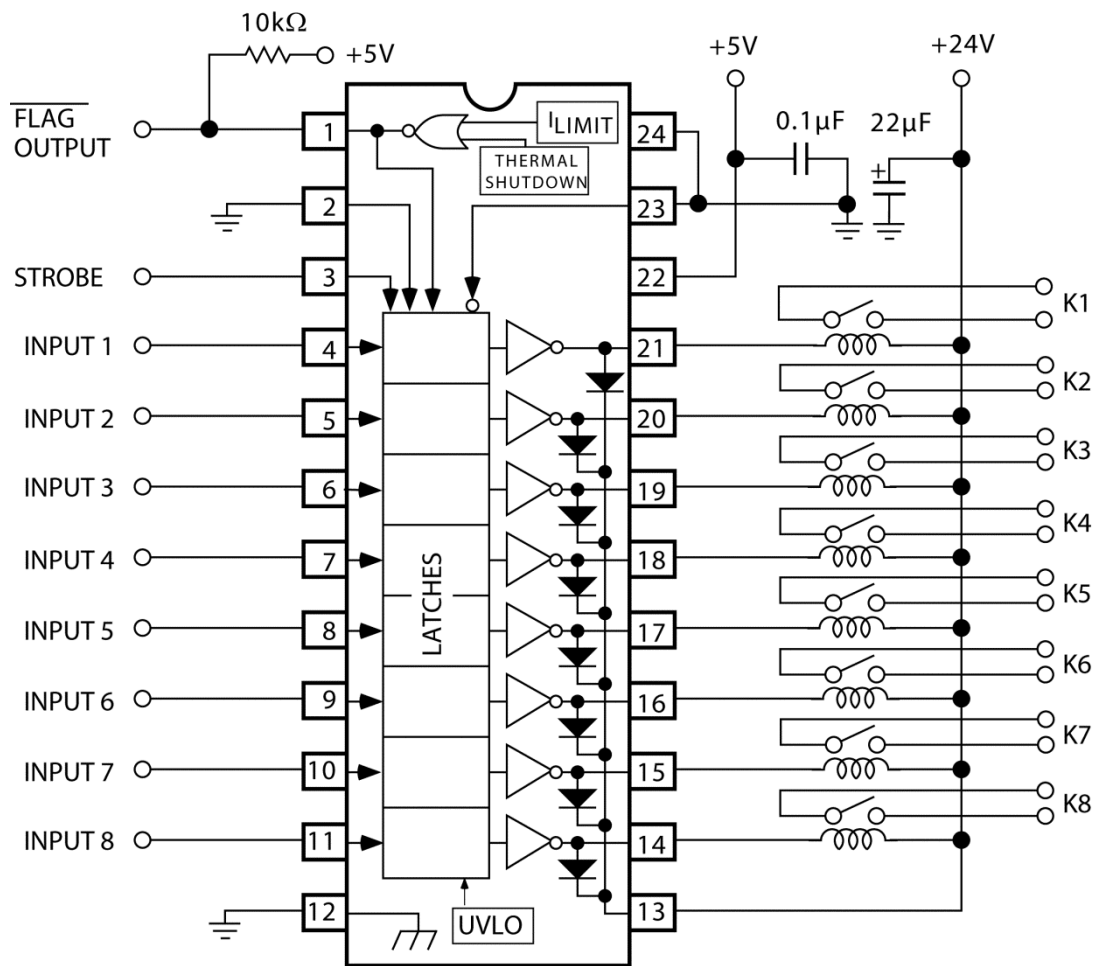
$T_A = +25^\circ\text{C}$; Logic levels are V_{DD} and V_{SS} ; $V_{DD} = 5\text{V}$.

A. Minimum data active time before strobe enabled (data set-up time)	50ns
B. Minimum data active time after strobe disabled (data hold time)	50ns
C. Minimum strobe pulse width	125ns
D. Typical time between strobe activation and output on-to-off transition	500ns
E. Typical time between strobe activation and output off-to-on transition	500ns
F. Minimum clear pulse width	300ns
G. Minimum data pulse width	225ns

Typical Characteristics

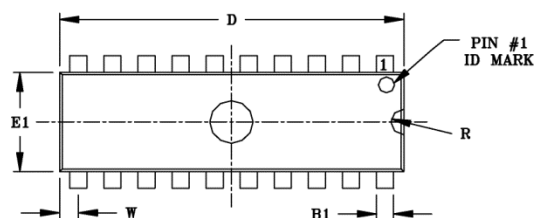


Typical Application

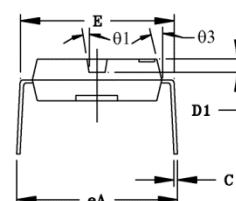
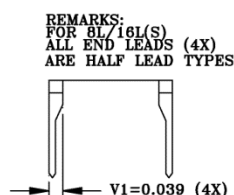


MIC59P50 Protected Relay Driver

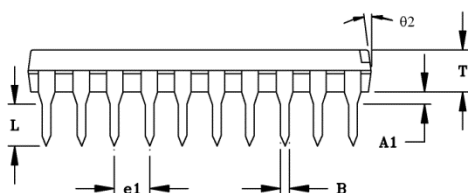
Package Information and Recommended Land Pattern⁽⁹⁾



TOP VIEW



END VIEW



SIDE VIEW

NOTE:

1. SPADE WIDTH, LEAD WIDTH AND LEAD THICKNESS EXCLUSIVE OF TIN PLATING OR SOLDER PLATING/ DIPPING THICKNESS.
2. PACKAGE OUTLINE EXCLUSIVE OF ANY MOLD FLASHES.
3. PACKAGE OUTLINE EXCLUSIVE OF BURR DIMENSION.
4. * - REFERENCE DIMENSION.
5. PACKAGE AND FINISHING : TOP, BOTTOM & ALL SIDE: MATTE VDI #24~27.

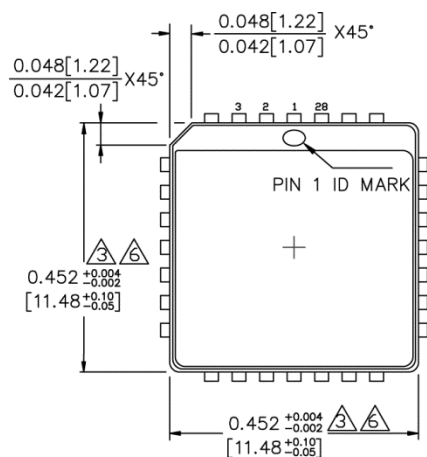
LEAD TYPE		8LD	14/16LD	18LD	20LD	24LD
STAND-OFF	A1	0.015 MIN	0.015 MIN	0.015 MIN	0.015 MIN	0.015 MIN
LEAD WIDTH *	B	0.018	0.018	0.018	0.018	0.018
SPADE WIDTH *	B1	0.060	0.060	0.060	0.060	0.060
LEAD THICKNESS *	C	0.010	0.010	0.010	0.010	0.012
LENGTH TOL ±0.004	D	0.375	0.750	0.890	1.020	1.250
IDENT DEPTH	D1	0.030 ~ 0.060	0.030 ~ 0.060	0.030 ~ 0.060	0.030 ~ 0.060	0.030 ~ 0.060
SHOULDER WIDTH OUTER TO OUTER	E	0.300 ~ 0.325	0.300 ~ 0.325	0.300 ~ 0.325	0.300 ~ 0.325	0.300 ~ 0.325
WIDTH TOL ±0.004	E1	0.250	0.250	0.250	0.250	0.250
LEAD SPREAD OUTER TO OUTER	eA	0.320 ~ 0.370	0.320 ~ 0.370	0.320 ~ 0.370	0.320 ~ 0.370	0.320 ~ 0.370
LEAD PITCH *	e1	0.100	0.100	0.100	0.100	0.100
LEAD LENGTH TOL ±0.004	L	0.125	0.125	0.125	0.125	0.125
IDENT RADIUS	R	0.030	0.030	0.030	0.030	0.030
TOTAL THICKNESS TOL ±0.004	T	0.130	0.130	0.130	0.130	0.130
LEAD TO END PACKAGE	W	0.025 REF	0.075REF14LD 0.025REF16LD	0.045REF	0.060REF	0.075REF
IDENT DRAFT TOL ±3°	θ1	7°	7°	7°	7°	7°
END ANGLE (4x) TOL ±3°	θ2	7°	7°	7°	7°	7°
SIDE ANGLE (4x) TOL ±3°	θ3	7°	7°	7°	7°	7°

24-Pin PDIP (N)

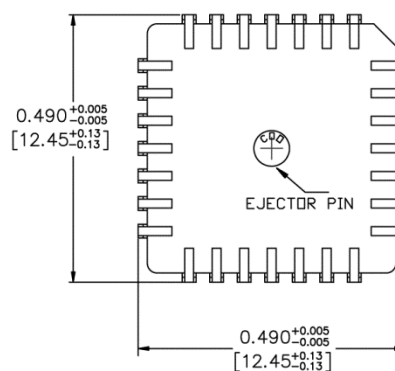
Note:

9. Package information is correct as of the publication date. For updates and most current information, go to www.micrel.com.

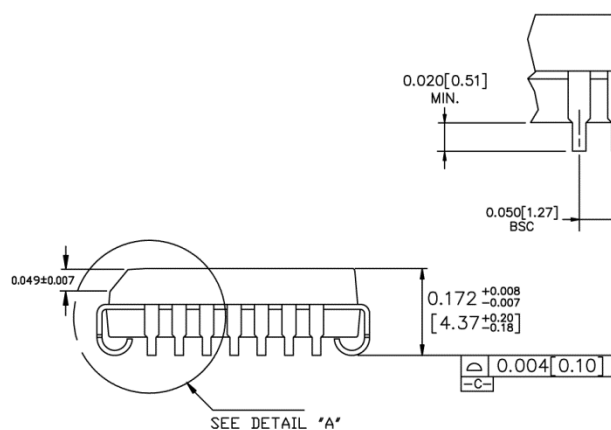
Package Information and Recommended Land Pattern⁽⁹⁾



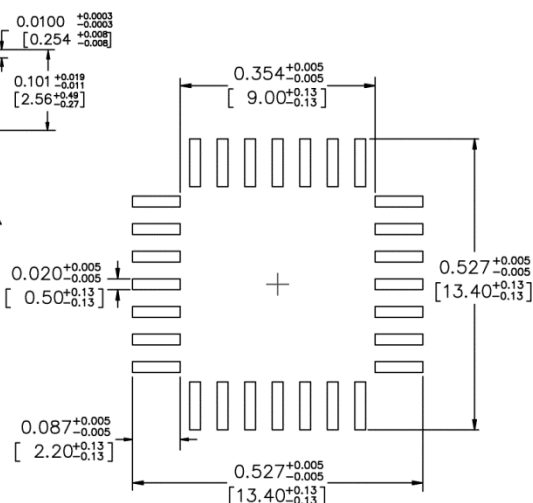
TOP VIEW



BOTTOM VIEW



SIDE VIEW



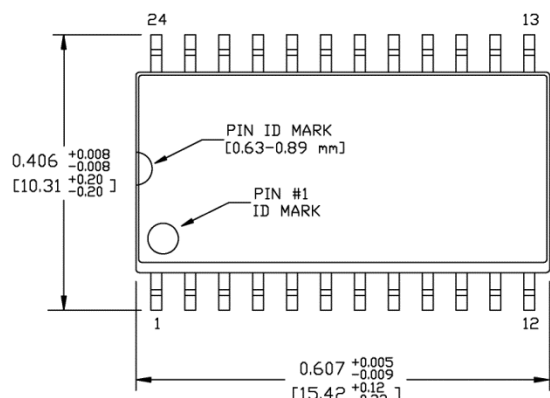
RECOMMENDED LAND PATTERN

NOTES:

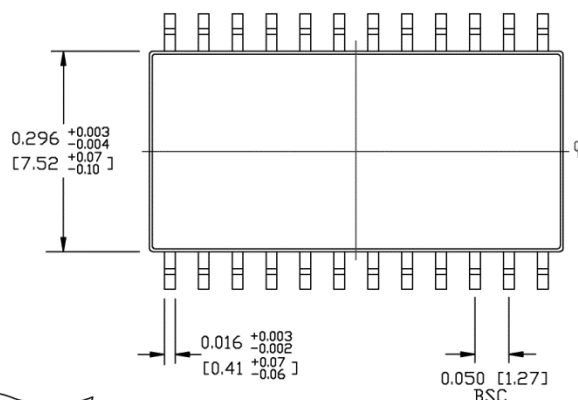
1. DIMENSIONS ARE IN INCHES [MM].
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS, EITHER OF WHICH SHALL NOT EXCEED 0.008 [0.203].
4. LEAD DIMENSION DOES NOT INCLUDE DAMBAR PROTRUSION.
5. MAXIMUM AND MINIMUM SPECIFICATIONS ARE INDICATED AS FOLLOWS : MAX/MIN
6. PACKAGE TOP DIMENSION MAY BE SLIGHTLY SMALLER THAN BOTTOM DIMENSION.

28-Pin PLCC (V)

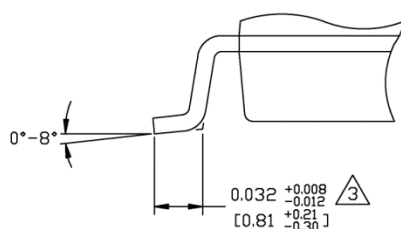
Package Information and Recommended Land Pattern⁽⁹⁾



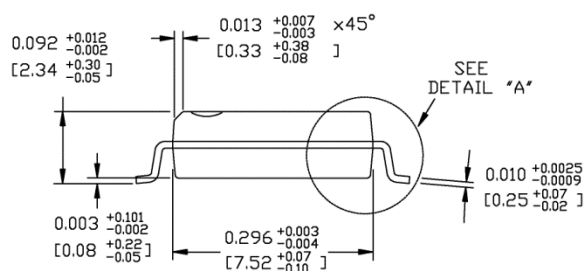
TOP VIEW
NOTE: 1, 2



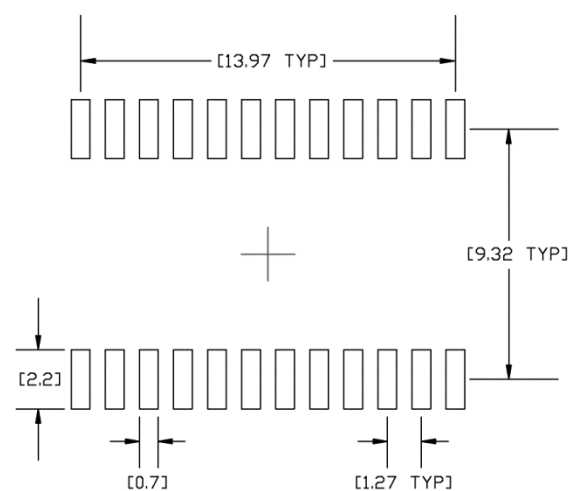
BOTTOM VIEW
NOTE: 1, 2



DETAIL "A"



END VIEW
NOTE: 1, 2, 3



RECOMMENDED LAND PATTERN

NOTES:

1. DIMENSIONS ARE IN INCHES[MM].
2. CONTROLLING DIMENSION: INCHES.
3. DIMENSION DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS, EITHER OF WHICH SHALL NOT EXCEED 0.006[0.15] PER SIDE.

24-Pin Wide SOIC (WM)

MICREL, INC. 2180 FORTUNE DRIVE SAN JOSE, CA 95131 USA
TEL +1 (408) 944-0800 FAX +1 (408) 474-1000 WEB <http://www.micrel.com>

Micrel, Inc. is a leading global manufacturer of IC solutions for the worldwide high performance linear and power, LAN, and timing & communications markets. The Company's products include advanced mixed-signal, analog & power semiconductors; high-performance communication, clock management, MEMs-based clock oscillators & crystal-less clock generators, Ethernet switches, and physical layer transceiver ICs. Company customers include leading manufacturers of enterprise, consumer, industrial, mobile, telecommunications, automotive, and computer products. Corporation headquarters and state-of-the-art wafer fabrication facilities are located in San Jose, CA, with regional sales and support offices and advanced technology design centers situated throughout the Americas, Europe, and Asia. Additionally, the Company maintains an extensive network of distributors and reps worldwide.

Micrel makes no representations or warranties with respect to the accuracy or completeness of the information furnished in this datasheet. This information is not intended as a warranty and Micrel does not assume responsibility for its use. Micrel reserves the right to change circuitry, specifications and descriptions at any time without notice. No license, whether express, implied, arising by estoppel or otherwise, to any intellectual property rights is granted by this document. Except as provided in Micrel's terms and conditions of sale for such products, Micrel assumes no liability whatsoever, and Micrel disclaims any express or implied warranty relating to the sale and/or use of Micrel products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

Micrel Products are not designed or authorized for use as components in life support appliances, devices or systems where malfunction of a product can reasonably be expected to result in personal injury. Life support devices or systems are devices or systems that (a) are intended for surgical implant into the body or (b) support or sustain life, and whose failure to perform can be reasonably expected to result in a significant injury to the user. A Purchaser's use or sale of Micrel Products for use in life support appliances, devices or systems is a Purchaser's own risk and Purchaser agrees to fully indemnify Micrel for any damages resulting from such use or sale.

© 1998 Micrel, Incorporated.